

ATTORNEY DOCKET NO.: ASC-049C1

APPLICANT(S): Fitzgerald

SERIAL NO.: 10/774,890

FILING DATE: February 9, 2004

GROUP: 2818

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EXAM. INIT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
UH	A170	2002/0063292	05/30/2002	Armstrong et al.	e		
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FORM PTO – 1449					ATTORNEY DOCKET NO.: ASC-013							
SUPPLEMENTAL INFORMATION					APPLICANT(S): Bulsara et al.							
DISCLO	SURE	STATEMENT	SERIAL N	IO.: 10/2	18,007							
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	C108	Huang, et al., "Reduction of Source/Drain Series Resistance and Its Impact on Device Performance for PMOS Transistors with Raised Si _{1-x} Ge _x Source/Drain", <u>IEEE Electron Device Letters</u> , Vol. 21, No. 9, (Sept. 2000) pp. 448-450.										
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		C114	Öztürk, et al., "Adv International Electr							Sub-70 nm	CMOS	," <u>IEEE</u>		
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